



(0,635 mm) .025"

QTS SERIES

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTS

Insulator Material:

Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Current Rating:

Contact:

1.8 A per pin

(1 pin powered per row)

Ground Plane:

23.1 A per ground plane

(1 ground plane powered)

Operating Temp:

-55°C to +125°C

Voltage Rating: 285 VAC

Max Cycles: 100

RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (025-075)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

Board Mates:

QSS

Cable Mates:

SQCD

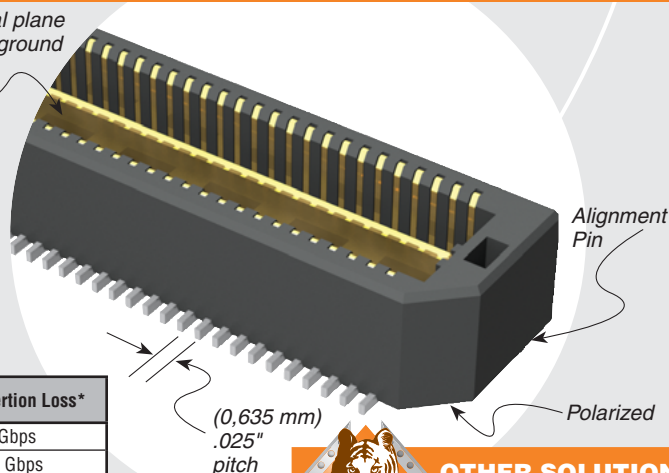


QTS/QSS 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	-D	9 GHz / 18 Gbps
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps

*Performance data includes effects of a non-optimized PCB.

Performance data for other stack heights and complete test data available at www.samtec.com?QTS or contact sig@samtec.com

Integral metal plane
for power or ground



(0,635 mm)
.025"
pitch

Alignment
Pin

Polarized



OTHER SOLUTIONS

• Board spacing
standoffs
(See SO Series)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount

Contact Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

QTS	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
-----	--------------------------	------------	----------------	---	---	--------------

-025, -050, -075
(50 total positions per bank)

Specify
LEAD
STYLE
from
chart.

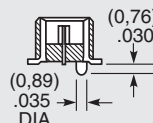
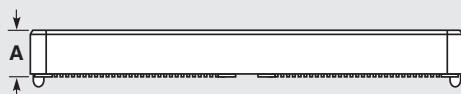
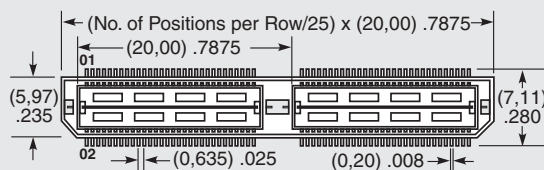
-F
= Gold Flash on Signal Pins
and Ground Plane,
Matte Tin on tails

-L
= 10µ" (0,25 µm) Gold on Signal
Pins and Ground Plane,
Matte Tin on tails

-C*
= Electro-Polished Selective
50µ" (1,27 µm) min Au over
150µ" (3,81 µm) Ni on Signal
Pins in contact area,
10µ" (0,25 µm) min Au over
50µ" (1,27 µm) Ni on Ground
Plane in contact area,
Matte Tin over 50µ" (1,27 µm)
min Ni on all solder tails

-K
= (7,00 mm)
.275" DIA
Polyimide film
Pick &
Place Pad

-TR
= Tape & Reel



STACK HEIGHTS		
LEAD STYLE	A	MATED HEIGHT
-01	(4,27) .168	(5,00) .197
-02	(7,26) .286	(8,00) .315

Processing conditions will affect mated height.